

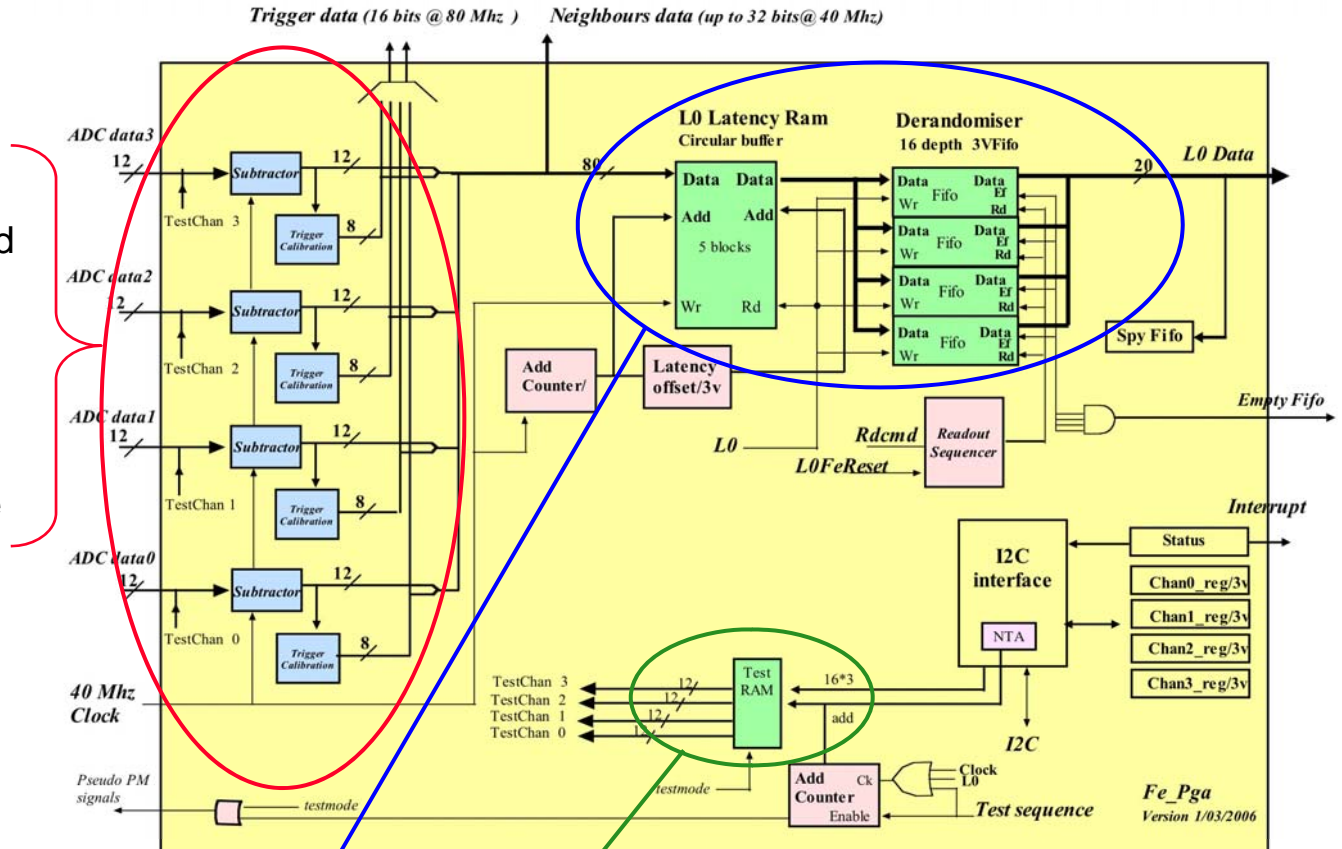
Choice of Front-End FPGA

- ◆ **ECAL/HCAL Front-END Card : FEPGA functionalities reminder**
- ◆ **Integrated Design Environment :**
 - IDE Actel Libero
 - Debug tools : Identify, Silicon explorer (Actel antifuse only !)
- ◆ **Axcelerator family (current Front end FPGA)**
 - Device architecture reminder
 - Layout : Front-end FPGA firmware inside AX250
- ◆ **PA3 family**
 - Device architecture
 - Example of Front-end FPGA firmware inside A3PE600
 - Estimation of needed resource in PA3 family
 - Possible target
 - Compilation inside possible target
 - Possibilities of migration inside PA3 family
- ◆ **Summary table (price, resources, ..)**

FrontEnd PGA functionalities : reminder

◆ 4 functional blocks :

- The first one processes the input ADC data, which needs to be re-synchronized (each ADC has its own clock), and processed to remove the low frequency noise and to subtract the pedestal
- The second block produces the trigger data, converting the 12 bits of the ADC to 8 bits



- The third block is in charge of storing the data (80 bits per FE-PGA) during the L0 latency, and to send it up upon L0-Yes to the SEQ-PGA

- The last block permits injecting test values at the input, in place of the ADC values, in order to check the proper behaviour of the card.

LHCb FEB note : Christophe, Frédéric, Jacques, ...

Actel Libero : Integrated Design Environment

Actel FPGA : Radhard

The screenshot displays the Actel Libero IDE interface. At the top, the menu bar includes File, Edit, View, Project, Import IP, Run, Analysis, HDL-analyst, Options, Window, TechSupport, and Help. The main workspace is divided into several panes:

- Design Explorer:** Shows a hierarchical tree of project files, including HDL Source Files and User Files.
- Design Entry Tools:** Contains icons for I/O Attribute Editor, HDL Editor, SmartDesign, and ViewDraw.
- Root: feppga:** A central flow diagram showing the design process: Source Files (feppga.edn) → Synthesis (Synplify) → Post-Synthesis Files → Place&Route (Designer) → Post-Layout Files → Programming (FlashPro, Identity Debugger, Silicon Sculptor).
- Simulation:** Includes Simulation (ModelSim) and Stimulus (WaveFormer HDL Editor).
- Properties:** A panel on the right showing details for the selected component.
- Information Window:** Displays project management options like Project Manager, I/O Attribute Editor, Tool Profiles, Enhance IP, Cores, Updates, CoreConsole, Project, C, SmartDesign, and SmartAS.
- Designer (feppga.adb):** A detailed view of the design flow with steps: Compile, Layout, Back-Annotate, and Programming File. It also includes a Multiview Navigator with Netlist Viewer, PinEditor, ChipPlanner, I/O Attribute Editor, SmartTime, Constraints Editor, Timing Analyzer, and Smart Power.
- ModelSim:** A window showing the simulation environment with a Verilog script and a console window displaying error messages.

Red annotations highlight key components:

- LIBERO IDE:** A red circle around the top menu bar.
- Synplify : synthesis tools:** A red circle around the Synplify icon in the Design Entry Tools pane.
- ModelSim : simulation tools:** A red circle around the ModelSim icon in the Simulation pane.
- Designer : Place&Route tools:** A red circle around the Designer icon in the Design Entry Tools pane.

Text annotations include:

- Manage your project files and components* (blue text) pointing to the Design Explorer.
- FrontEnd LHCb upgrade* (black text) at the bottom center.
- April 7-8 2009* (black text) at the bottom right.
- LINEAIRE* (black text) at the bottom right.

Debug tools : Silicon Explorer - Identify

Silicon Explorer :

Integrated verification and logic analysis tool
for antifuse devices ONLY



Silicon Explorer shortens the FPGA design verification process by providing a tightly integrated suite of tools and capabilities that enable rapid isolation of functional and timing problems



There's no need to re-layout, recompile, or redo any part of your design to complete the verification process.

Christophe, Frédéric and Jacques are expert !

Identify : (free)

In-system debugging tool for Actel's flash devices

Identify implementation :

- Need to recompile and re-layout a part of your design (incremental option)
- Use logic and RAM block of the device
- Read data spied by JTAG

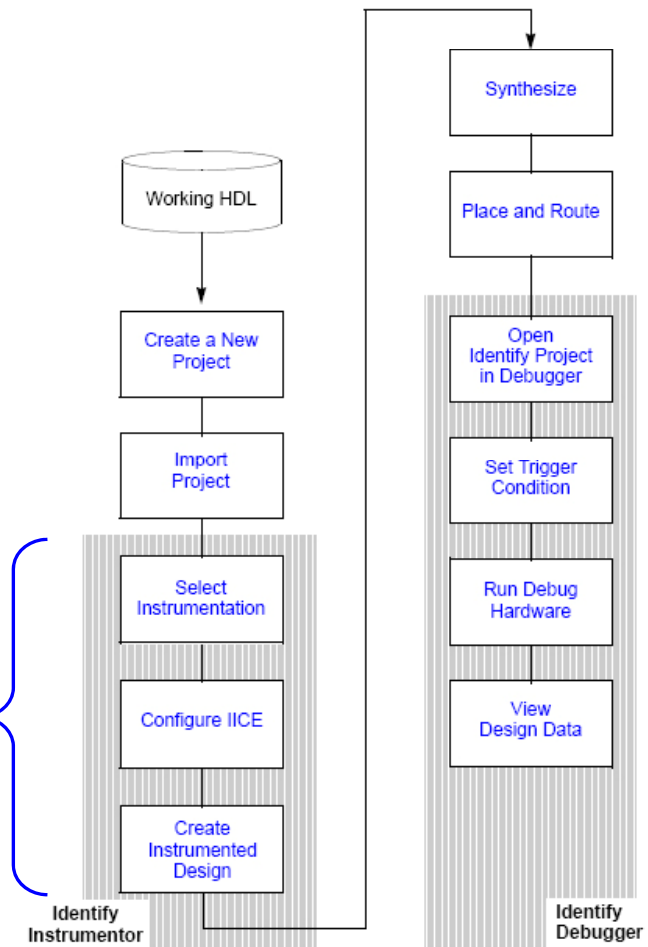


Figure 1: Identify RTL Debugger Design Flow

Accelerator Family device architecture (antifuse technology)

Basic cell : SuperCluster

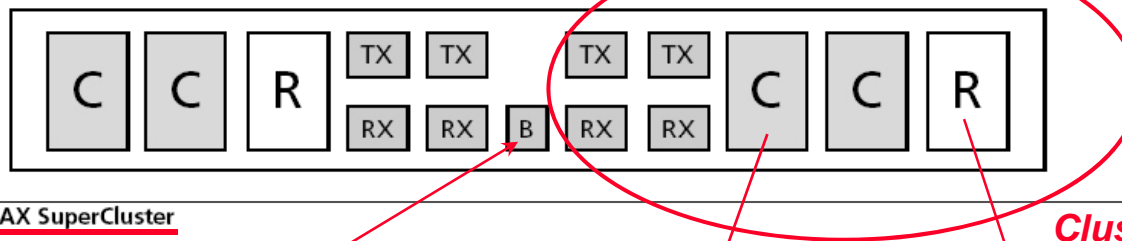
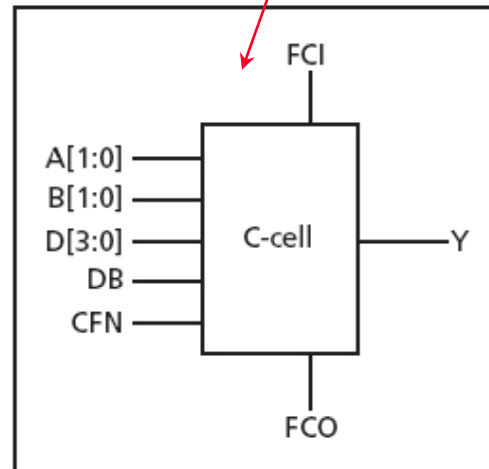


Figure 1-4 • AX SuperCluster

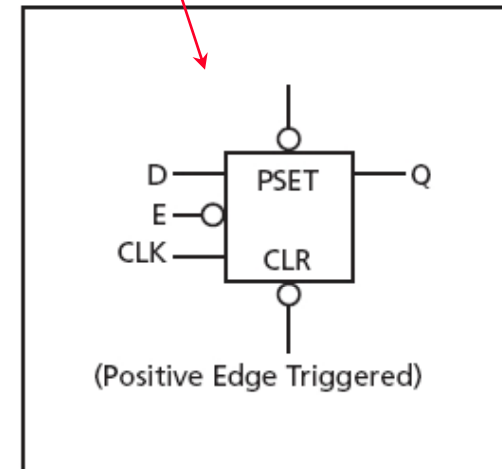
Independent Buffer

Cluster :

- 2 x C-Cells
- 1 x R-Cell
- 2x TX (Transmit buffers)
- 2x RX (Receive buffers)



Combinatorial cell



Register cell

Axcelerator Family device architecture (antifuse technology)

Axcelerator Family FPGAs

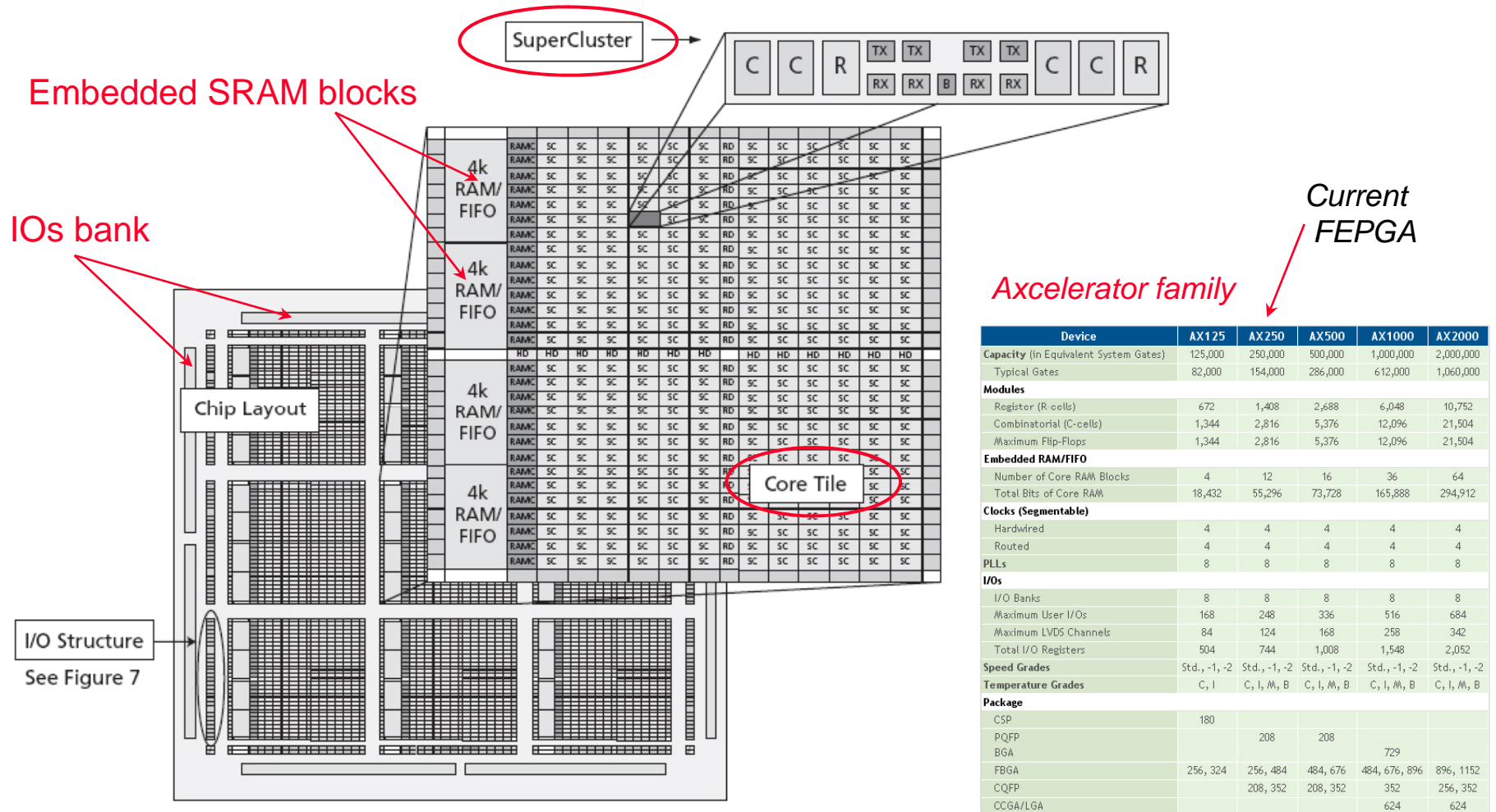
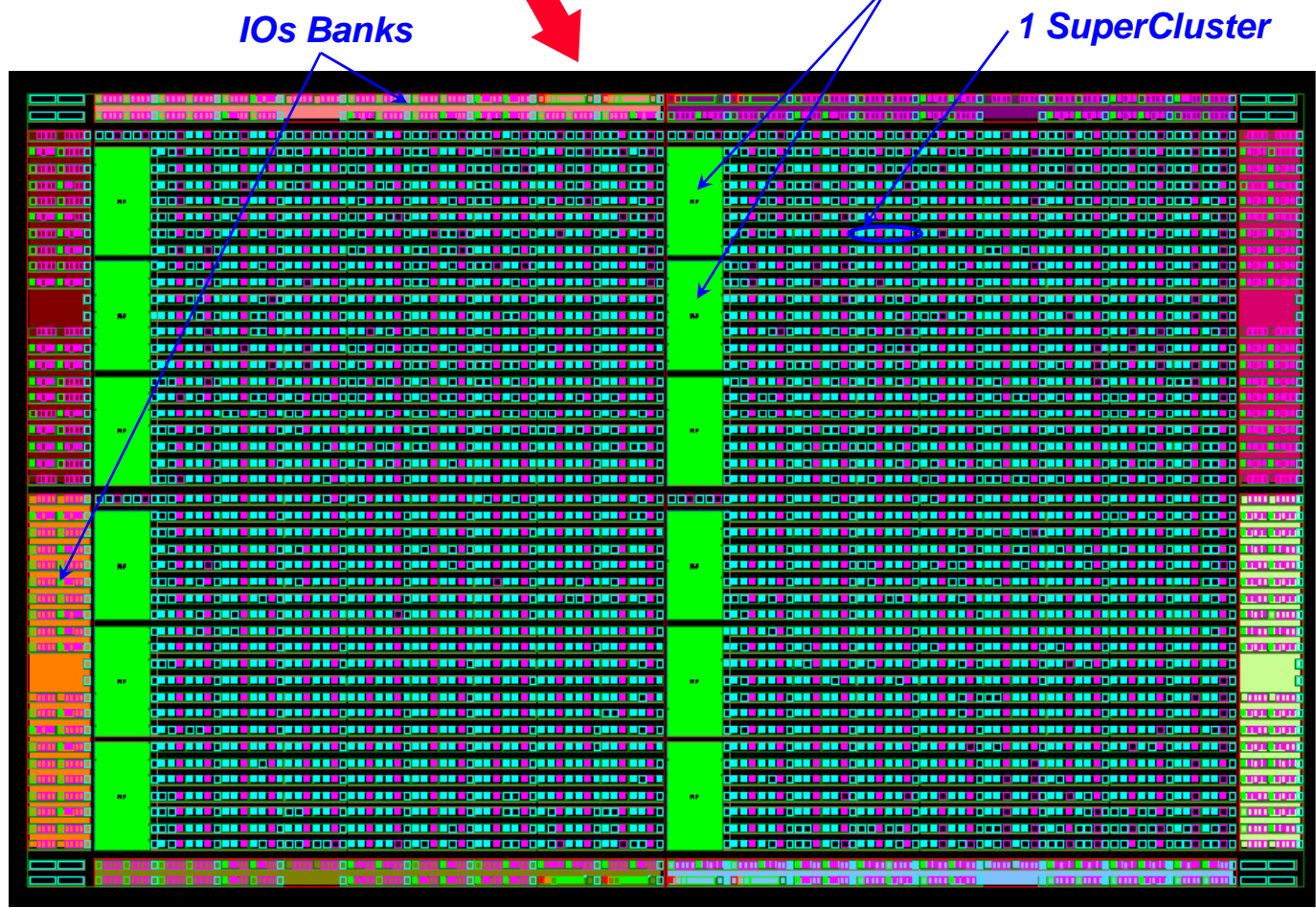
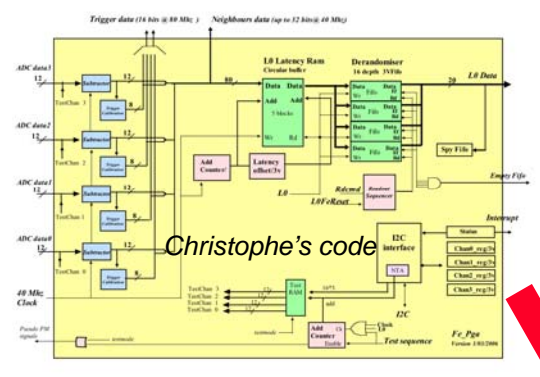


Figure 1-6 • AX Device Architecture (AX1000 shown)

FPGA firmware inside AX250



Compile report:

=====
 Family : Axcelerator
 Device : **AX250**
 Package : **484 FBGA**

Post-Combiner device utilization:

- SEQUENTIAL (R-cells)
Used: 1249 Total: 1408 **(88.71%)**
- COMB (C-cells)
Used: 2181 Total: 2816 **(77.45%)**
- LOGIC (R+C cells)
Used: 3430 Total: 4224 **(81.20%)**
- RAM/FIFO Used: 12 Total: 12
- IO w/Clocks Used: 148 Total: 248
- CLOCK (Routed) Used: 3 Total: 4
- PLL Used: 2 Total: 8
- Input I/O Register : 0
- Output I/O Register : 0
- DDR Register : 0
- Comb-Comb (CC) : 0
- Carry Chain : 65

I/O Information:

- Input Pads : 63
- Output Pads : 84
- Bidirectional Pads : 1
- Differential Input Pairs : 0
- Differential Output Pairs : 0



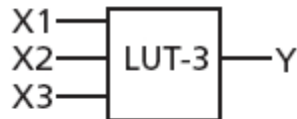
ProASIC3 Family device architecture (Flash technology)

Basic cell : VersaTile

Each Versatile can be configured as :
(by programming the appropriate flash
switch interconnections)

- A three input logic function

LUT-3 Equivalent



- A D-flip-flop
(with or without enable)

D-Flip-Flop with Clear or Set



- A latch

Enable D-Flip-Flop with Clear or Set

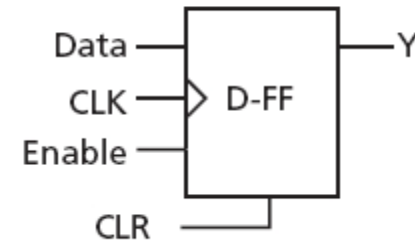


Figure 1-2 • VersaTile Configurations

ProASIC3 Family architecture (Flash technology)

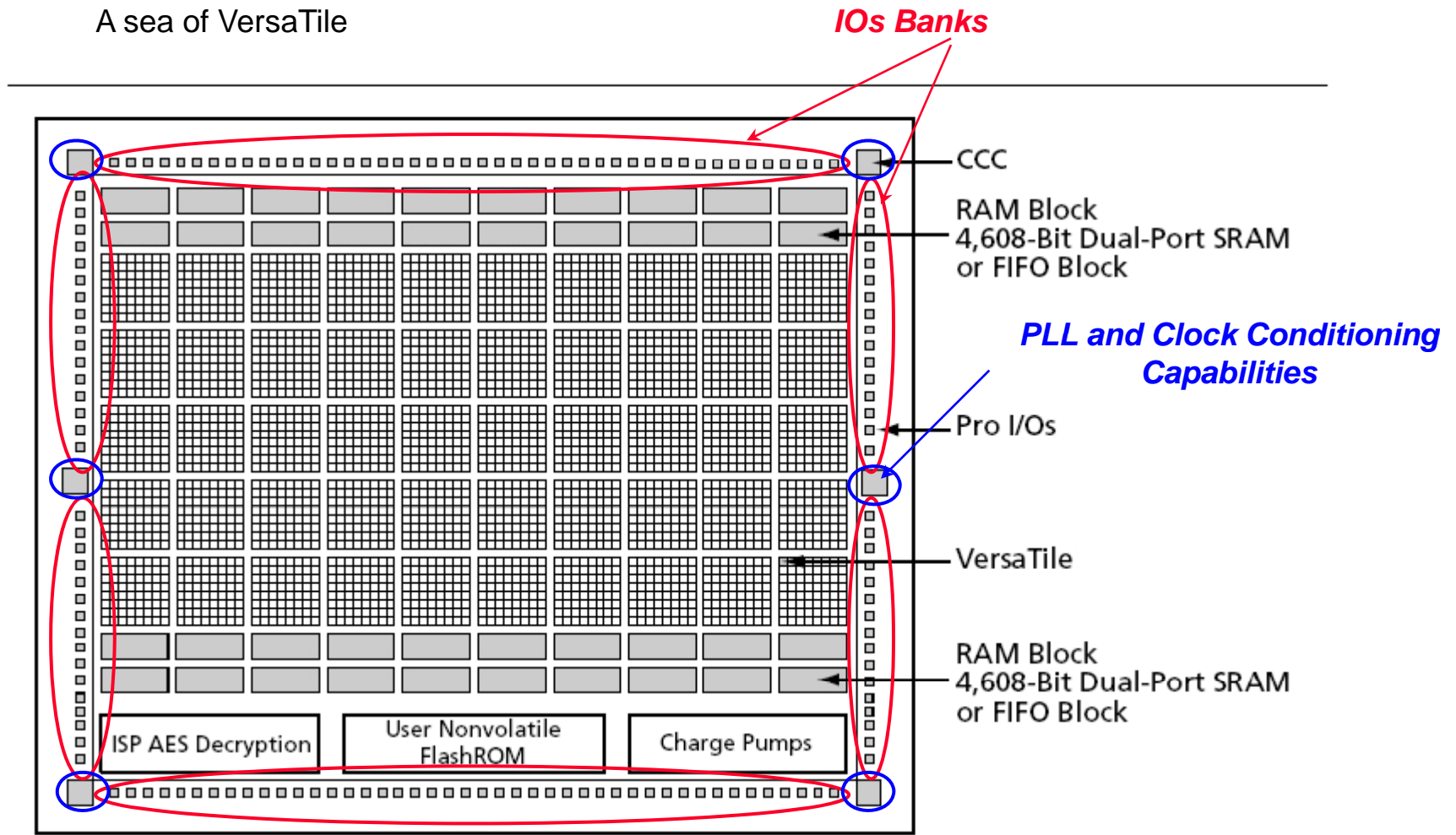
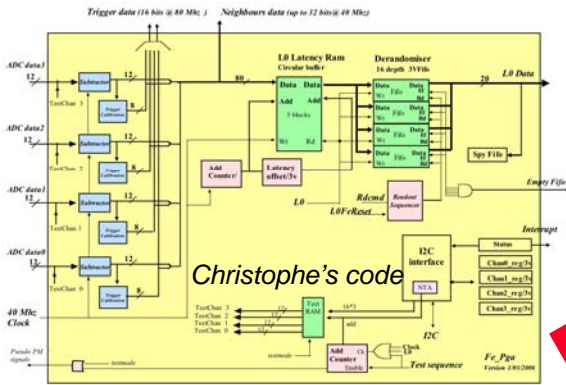


Figure 1-1 • ProASIC3E Device Architecture Overview

Example of FEPGA firmware inside PA3E: A3PE600



Compile report:

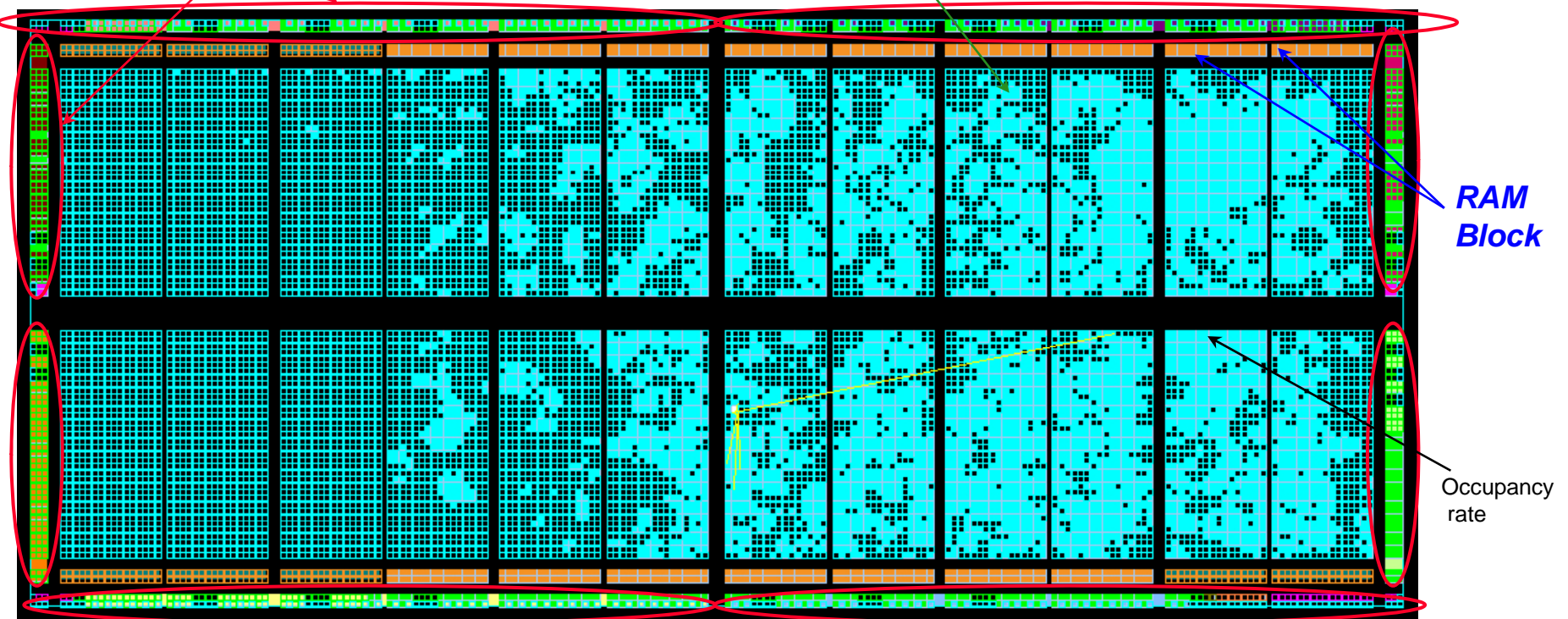
• CORE(VersaTiles) :	Used: 5374	Total: 13824 (38.87%)
• IO (W/ clocks)	Used: 147	Total: 270 (54.44%)
• Differential IO	Used: 0	Total: 135 (0.00%)
• GLOBAL (Chip+Quadrant)	Used: 6	Total: 18 (33.33%)
• PLL	Used: 2	Total: 6 (33.33%)
• RAM/FIFO	Used: 16	Total: 24 (66.67%)

x 1.6 (R+C Cells)

IOs Banks

VersaTiles

Family : ProASIC3E
Device : A3PE600
Package : 484 FBGA



Estimation of needed resources in ProASIC3 family

	Curent FEPGA 4 Channels (AX250)	Futur FEPGA 8 Channels (PA3 Family ?)	Futur FEPGA 8 Channels (AX 500) <i>(BackUp solution !)</i>
IOs	148	~ 260 <i>(Jacques calculation !)</i>	317 (FG 484) 336 (FG 676)
IOs Banks	8	8 <i>4 is too few considering IOs diversity (GBT, ADC, ...)</i>	8
RAM Blocks	12 (L0 Latency Derandomiser)	~ 26 <i>Packing (~24) Test RAM (~2)</i>	16
Cells	3430 (R+C Cells) (~ 5374 Versatiles)	~ 11000 Versatiles	8064 (R+C Cells)
PLL	8 (used: 2)	1 ?	8

IOs : 96 ADC + 32 Trigger + 48 neighbour + (58 ou 28) GBT + 21 Divers = 253 ou 225

Packing : 96 bits during N samples if N=1024 => 24 Blocks RAM

Possible target in A3P family

ProASIC3 Devices	A3P015	A3P030	A3P060	A3P125	A3P250	A3P400	A3P600	A3P1000
CoreMP7 Devices								M7A3P1000
Cortex-M1 Devices					M1A3P250	M1A3P400	M1A3P600	M1A3P1000
System Gates	15,000	30,000	60,000	125,000	250,000	400,000	600,000	1,000,000
Typical Equivalent Macrocells	128	256	512	1,024	2,048	–	–	–
VersaTiles (D-Flip-Flop)	384	768	1,536	3,072	6,144	9,216	13,824	24,576
RAM kbits (1,024 bits)	–	–	18	36	36	54	108	144
4,608-Bit Blocks	–	–	4	8	8	12	24	32
FlashROM Bits	1,024	1,024	1,024	1,024	1,024	1,024	1,024	1,024
Secure (AES) ISP ¹	–	–	Yes	Yes	Yes	Yes	Yes	Yes
PLLs	–	–	1	1	1	1	1	1
VersaNet Globals ²	6	6	18	18	18	18	18	18
I/O Standards	Std. & Hot Swap	Std. & Hot Swap	Std.+	Std.+	Std.+/ LVDS	Std.+/ LVDS	Std.+/ LVDS	Std.+/ LVDS
I/O Banks (+JTAG)	2	2	2	2	4	4	4	4
Maximum User I/Os	49	81	96	133	157	194	235	300
Speed Grades	-F, Std.	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2
Temperature Grades	C, I	C, I	C, I, T	C, I, T	C, I, T	C, I	C, I	C, I, T, M
Single-Ended I/Os / Differential I/O Pairs								
QN48		34						
QN68	49	49						
QN132		81	80	84	87/19 ³			
VQ100		77	71	71	68/13			
TQ144			91	100				
PQ208				133	151/34	151/34	154/35	154/35
FG144			96	97	97/24	97/25	97/25	97/25
FG256					157/38 ³	178/38	177/43	177/44
FG484						194/38	235/60	300/74

1.5 V core operation

A3P1000
Pb number of bank !

4 is too few considering IOs diversity (GBT, ADC, ...)

Possible target in A3PE family

ProASIC3E Devices	A3PE600	A3PE1500	A3PE3000
Cortex-M1 Devices		M1A3PE1500	M1A3PE3000
System Gates	600,000	1,500,000	3,000,000
VersaTiles (D-Flip-Flop)	13,824	38,400	75,264
RAM kbits (1,024 bits)	108	270	504
4,608-Bit Blocks	24	60	112
FlashROM Bits	1,024	1,024	1,024
Secure (AES) ISP	Yes	Yes	Yes
Integrated PLL in CCCs ¹	6	6	6
VersaNet Globals ²	18	18	18
I/O Standards	Pro	Pro	Pro
I/O Banks (+JTAG)	8	8	8
Maximum User I/Os	270	444	620
Speed Grades	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2
Temperature Grades	C, I	C, I	C, I
Single-Ended I/O / Differential I/O Pairs			
PQ208	147/65	147/65	147/65
FG256	165/79		
FG324			221/110
FG484	270/135	280/139	341/168
FG676		444/222	
FG896			620/310

- 1.5 V core operation
- Bigger than A3P

A3PE1500
Good candidat !

A3PE3000
• Oversize
• Pb of price !

Possible target in A3PL family

ProASIC3L Devices	A3P250L	A3P600L	A3P1000L	A3PE600L	A3PE3000L
Cortex-M1 Devices		M1A3P600L	M1A3P1000L		M1A3PE3000L
System Gates	250,000	600,000	1,000,000	600,000	3,000,000
VersaTiles (D-Flip-Flop)	6,144	13,824	24,576	13,824	75,264
RAM kbits (1,024 bits)	36	108	144	108	504
4,608-Bit Blocks	8	24	32	24	112
FlashROM Bits	1,024	1,024	1,024	1,024	1,024
Secure (AES) ISP ¹	Yes	Yes	Yes	Yes	Yes
Integrated PLLs in CCCs ²	1	1	1	6	6
VersaNet Globals	18	18	18	18	18
I/O Standards	Std./LVDS	Std./LVDS	Std./LVDS	Pro	Pro
I/O Banks (+JTAG)	4	4	4	8	8
Maximum User I/Os	157	235	300	270	620
Typical Static / Flash*Freeze Power (mW) at V _{CC} =1.2 V	0.33	0.66	1.06	TBA	3.30
Speed Grades	Std., -1	Std., -1	Std., -1	Std., -1	Std., -1
Temperature Grades	C, I	C, I	C, I	M	C, I, M
Single-Ended I/Os / Differential I/O Pairs					
VQ100	68/13				
PQ208	151/34	154/35	154/35		147/65 ²
FG144	97/24	97/25	97/25		
FG256	157/38	177/43	177/44		
FG324					221/110
FG484		235/60	300/74	270/135	341/168
FG896					620/310

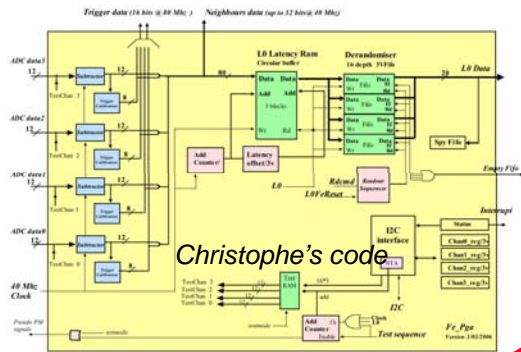
Low power 1.2 to 1.5 V core operation

4 is too few considering I/Os diversity (GBT, ADC, ...)

A3P1000
Pb number of bank !

A3PE3000
• Oversize
• Pb of price !

Compilation inside possible target : A3PE1500

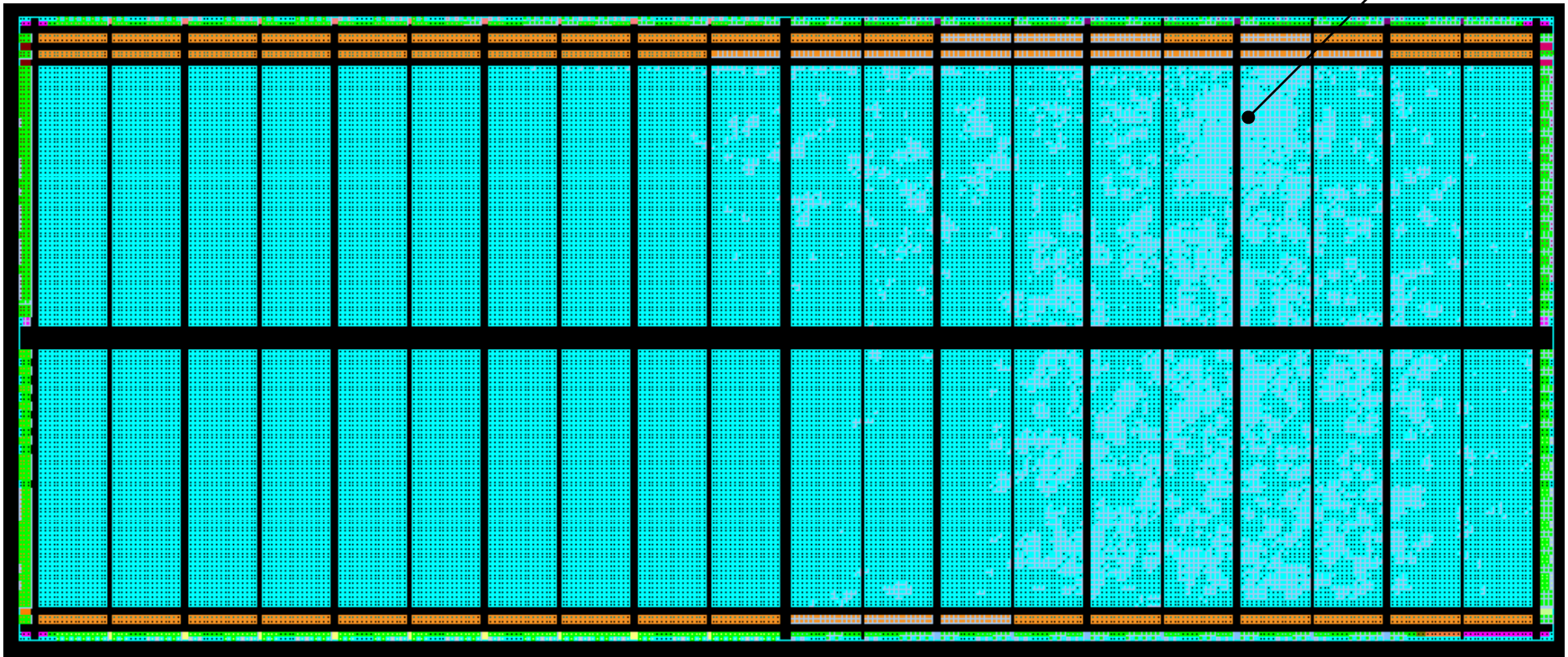


Family : ProASIC3E
 Device : A3PE1500
 Package : 484
 FBGA

Compile report:

CORE	Used: 5374	Total: 38400 (13.99%)
IO (W/ clocks)	Used: 147	Total: 280 (52.50%)
Differential IO	Used: 0	Total: 139 (0.00%)
GLOBAL (Chip+Quadrant)	Used: 6	Total: 18 (33.33%)
PLL	Used: 2	Total: 6 (33.33%)
RAM/FIFO	Used: 16	Total: 60 (26.67%)
Low Static ICC	Used: 0	Total: 1 (0.00%)
FlashROM	Used: 0	Total: 1 (0.00%)
User JTAG	Used: 0	Total: 1 (0.00%)

Occupancy
rate



Possibilities of migration inside A3P Family

ProASIC3 Devices	A3P015	A3P030	A3P060	A3P125	A3P250	A3P400	A3P600	A3P1000
CoreMP7 Devices								M7A3P1000
Cortex-M1 Devices					M1A3P250	M1A3P400	M1A3P600	M1A3P1000
System Gates	15,000	30,000	60,000	125,000	250,000	400,000	600,000	1,000,000
Typical Equivalent Macrocells	128	256	512	1,024	2,048	—	—	—
VersaTiles (D-Flip-Flop)	384	768	1,536	3,072	6,144	9,216	13,824	24,576
RAM kbits (1,024 bits)	—	—	18	36	36	54	108	144
4,608-Bit Blocks	—	—	4	8	8	12	24	32
FlashROM Bits	1,024	1,024	1,024	1,024	1,024	1,024	1,024	1,024
Secure (AES) ISP ¹	—	—	Yes	Yes	Yes	Yes	Yes	Yes
PLLs	—	—	1	1	1	1	1	1
VersaNet Globals ²	6	6	18	18	18	18	18	18
I/O Standards	Std. & Hot Swap	Std. & Hot Swap	Std.+	Std.+	Std.+/ LVDS	Std.+/ LVDS	Std.+/ LVDS	Std.+/ LVDS
I/O Banks (+JTAG)	2	2	2	2	4	4	4	4
Maximum User I/Os	49	81	96	133	157	194	235	300
Speed Grades	-F, Std.	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2	-F, Std., -1, -2
Temperature Grades	C, I	C, I	C, I, T	C, I, T	C, I, T	C, I	C, I	C, I, T, M
Single-Ended I/Os / Differential I/O Pairs								
QN48		34						
QN68	49	49						
QN132		81	80	84	87/19 ³			
VQ100		77	71	71	68/13			
TQ144			91	100				
PQ208				133	151/34	151/34	154/35	154/35
FG144			96	97	97/24	97/25	97/25	97/25
FG256					157/38 ³	178/38	177/43	177/44
FG484						194/38	235/60	300/74

Migration possible inside the same family :

- From higher to middle density device

Migration possibility between family :

- A3P1000 <-> A3P1000L except pin Flash freeze.
- A3P3000 <-> A3P3000L except pin Flash freeze.

Summary

	Package Pins	IOs Max	IO Bank	VersaTitles or R_Cells C_Cells	BlockRAM (4608 bits Blocks)	PLL	VersaTitles or R_Cells C_Cells used	Resource used with FEPGA firmware	Prices (PUHT for 1000)
AX250	484 FBGA	248	8	R_Cell : 1408 C_Cell : 2816	12	8	R_Cell : 1249 C_Cell : 2181	R_Cells : 89% C_Cells : 78% - 148 / 248 IOs	PUHT € 42.55
AX500	484 FBGA	317	8		16	8	R_Cell : 1249 (x2) C_Cell : 2181 (x2)		PUHT € 69.8\$
	(FG676)	336							
A3P1000	484 FBGA	300	4	24576	32	1	5390 (x2)	- 22% VersaTitles - 147 / 300 IOs	PUHT € 36.90
A3PE600	484 FBGA	270	8	13824	24	6	5374 (x2)	- 40% VersaTitles - 147 / 270 IOs	PUHT € 39.40
A3PE1500	484 FBGA	280	8	38400	60	6	5374 (x2)	- 14% VersaTitles - 147 / 270 IOs	PUHT € 92.10
	(FG676)	444							PUHT € 93.70
A3PE3000	484 FBGA	341	8	75264	112	6	5374 (x2)	- 7% VersaTitles - 147 / 341 IOs	PUHT € 198.10
	(FG896)	620							PUHT € 213.30
A3P1000L	484 FBGA	300	4	24576	32	1	5345 (x2)	- 22% VersaTitles - 147 / 300 IOs	PUHT € 49.40
A3PE3000L	484 FBGA	341	8	75264	112	6	5345 (x2)	- 7% VersaTitles - 147 / 341 IOs	PUHT € 222.30
	(FG896)	620							

Accelerator

A3P Family

Current FEPGA 4 Channels

*

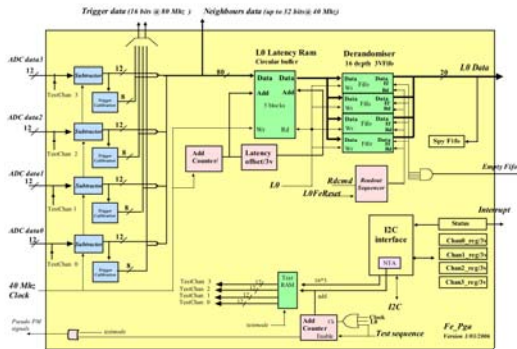
*

* LIBERO PLATINUM X 1 PUHT € 2495

For 8 Channels

Spares

FPGA firmware inside PA3: A3P1000



Family : ProASIC3
 Device : A3P1000
 Package : 484 FBGA

Compile report:

```

=====
CORE                Used: 5392 Total: 24576 (21.94%)
IO (W/ clocks)      Used: 147 Total: 300 (49.00%)
Differential IO      Used: 0 Total: 74 (0.00%)
GLOBAL (Chip+Quadrant) Used: 6 Total: 18 (33.33%)
PLL                  Used: 1 Total: 1 (100.00%)
RAM/FIFO             Used: 16 Total: 32 (50.00%)
Low Static ICC       Used: 0 Total: 1 (0.00%)
FlashROM             Used: 0 Total: 1 (0.00%)
User JTAG            Used: 0 Total: 1 (0.00%)
  
```

